(C) WPI / DERWENT

AN - 1993-041379 [05]

AP - JP19910143714 19910615; [Previous Publ. JP4367574]; JP19910143714 19910615.

CPY - SUMD

DC - L02

FS - CPI

IC - C04B37/00

MC - L02-A03 L02-J02C

PA - (SUMD) SUMITOMO CEMENT CO

PN - JP3192683B2 B2 20010730 DW200146 C04B37/00 006pp - JP4367574 A 19921218 DW199305 C04B37/00 007pp

PR - JP19910143714 19910615

XA - C1993-018804

XIC - C04B-037/00

AB - J04367574 Joining ceramic materials comprises forming a joint precursor between the opposing faces of ceramic material members and applying heat and pressure to reduce the thickness of the adhesive layer to that of the spacer layer, to tightly adhere the ceramic members with the plastically deformed adhesive layer.

 The precursor is composed of an inorganic adhesive layer capable of undergoing plastic deformation by heat and pressure and a thinner inorganic spacer layer which does not deform under heat and pressure.

 USE - Controls the thickness of the adhesive layer to achieve higher adhesion strength.(Dwg.0/5)

IW - JOIN CERAMIC MATERIAL JOINT PRECURSOR COMPRISE INORGANIC ADHESIVE LAYER PLASTICALLY DEFORM HEAT PRESSURE NON DEFORM INORGANIC SPACE LAYER

IKW - JOIN CERAMIC MATERIAL JOINT PRECURSOR COMPRISE INORGANIC ADHESIVE LAYER PLASTICALLY DEFORM HEAT PRESSURE NON DEFORM INORGANIC SPACE LAYER

NC - 001

OPD - 1991-06-15

ORD - 1992-12-18

PAW - (SUMD) SUMITOMO CEMENT CO

TI - Joining ceramic materials - using joint precursor comprising inorganic adhesive layer which is plastically deformed by heat and pressure and non-deformable inorganic spacer layer